



Material Content Data Sheet



Sales Product Name		BSS315P H6327		Issued		20. July 2018		
MA#		MA001636970						
Package		PG-SOT23-3-5		Weight*		9.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		470	
	noble metal	gold	7440-57-5	0.017	0.18		1823	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20659	22952
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		963	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	copper	7440-50-8	3.000	31.97	32.11	319742	321090
wire	non noble metal	copper	7440-50-8	0.045	0.48	0.48	4774	4774
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6049	
	plastics	epoxy resin	-	1.220	13.01		130059	
	inorganic material	silicondioxide	60676-86-0	4.399	46.88	60.49	468819	604927
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15947	15947
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30310	30310
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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